# WIRE BONDING OVER THE ACTIVE CIRCUIT AREA OF AN INTEGRATED CIRCUIT DEVICE


## ABSTRACT

Wire bonding over the active circuit (13) of an integrated circuit device (10) is accomplished by providing a layer of a polyimide material (23) in overlying relationship relative to the active circuit, depositing a bonding pad (31) on the polyimide layer opposite the active circuit, connecting the bonding pad electrically to the active circuit, and bonding a wire (33) to the bonding pad.


Figure 1.




This Sheet Has Been Replaced


